
DECLARATION - USA PATENT APPLICATION

As a below named inventor, I hereby declare that:

My residence, post office address and citizenship are as stated below next to my name;

I believe I am an original, first and joint inventor of the subject matter which is claimed

and for which a patent is sought on the invention entitled

AN INORGANIC POWDER-CONTAINING RESIN COMPOSITION, A FILM-FORMING MATERIAL LAYER, A TRANSFER SHEET, METHOD OF PRODUCING A SUBSTRATE HAVING A DIELECTRIC LAYER FORMED THEREON, AND A SUBSTRATE HAVING A DIELECTRIC LAYER FORMED THEREON

PCT Application No. PCT/JP2004/010483 filed in the Japanese Receiving Office on July 23, 2004; the documentation for entry into the U.S. national phase of which is attached hereto;

I hereby state that I have reviewed and understand the contents of the above identified specification, including the claims, as amended by any amendment referred to above;

I acknowledge the duty to disclose information which is material to patentability as defined in Title 37, Code of Federal Regulations, § 1.56;

I hereby claim foreign priority benefits under Title 35, United States Code, § 119(a)-(d) of any foreign application(s) for patent or inventor's certificate listed below and have also identified below any foreign application for patent or inventor's certificate having a filing date before that of the application on which priority is claimed:

PRIOR FOREIGN APPLICATION(S)

No.: 2003-279206

Country: Japan

Date Filed: 24/07/03

Priority
Claimed
Yes

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful, false statements may jeopardize the validity of the application or any patent issued thereon.

Full name of first inventor: Tomohide BANBA

Inventor's signature Tomohide Banba

Date November 1, 2005

Residence: **1-1-2, Shimohozumi, Ibaraki-shi, Osaka 567-8680 Japan**

Citizenship: **Japan**

Post Office Address: **Same as above**

Full name of second inventor: Katsuya KUME

Inventor's signature Katsuya Kume

Date November 1, 2005

Residence: **1-1-2, Shimohozumi, Ibaraki-shi, Osaka 567-8680 Japan**

Citizenship: **Japan**

Post Office Address: **Same as above**

Full name of third inventor: Makoto KAI

Inventor's signature Makoto Kai

Date November 1, 2005

Residence: **1-1-2, Shimohozumi, Ibaraki-shi, Osaka 567-8680 Japan**

Citizenship: **Japan**

Post Office Address: **Same as above**

Full name of forth inventor: Natsuki KOBAYASHI

Inventor's signature Natsuki Kobayashi

Date November 1, 2005

Residence: **1-1-2, Shimohozumi, Ibaraki-shi, Osaka 567-8680 Japan**

Citizenship: **Japan**

Post Office Address: **Same as above**

Full name of fifth inventor: Mami IKEYA

Inventor's signature Mami Ikeya

Date November 1, 2005

Residence: **1-1-2, Shimohozumi, Ibaraki-shi, Osaka 567-8680 Japan**

Citizenship: **Japan**

Post Office Address: **Same as above**

Full name of sixth inventor: Yasushi BUZOUJIMA

Inventor's signature Yasushi Buzoujima

Date November 1, 2005

Residence: **1-1-2, Shimohozumi, Ibaraki-shi, Osaka 567-8680 Japan**

Citizenship: **Japan**

Post Office Address: **Same as above**

Full name of seventh inventor: Junichi SEKIYA

Inventor's signature Junichi Sekiya

Date November 1, 2005

Residence: **1-1-2, Shimohozumi, Ibaraki-shi, Osaka 567-8680 Japan**

Citizenship: **Japan**

Post Office Address: **Same as above**

Full name of eighth inventor: Mitsuhiro KANADA

Inventor's signature Mitsuhiro Kanada

Date November 1, 2005

Residence: **1-1-2, Shimohozumi, Ibaraki-shi, Osaka 567-8680 Japan**

Citizenship: **Japan**

Post Office Address: **Same as above**

Send Correspondence To: Daniel E. Altman
KNOBBE, MARTENS, OLSON & BEAR, LLP
Customer No. 20,995

UNIU79.064APC

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant : Tomohide BANBA, et al.)
)
App. No. : Unknown)
)
Filed : Herewith)
)
For : **AN INORGANIC POWDER-
CONTAINING RESIN COMPOSITION,
A FILM-FORMING MATERIAL
LAYER, A TRANSFER SHEET,
METHOD OF PRODUCING A
SUBSTRATE HAVING A DIELECTRIC
LAYER FORMED THEREON, AND A
SUBSTRATE HAVING A DIELECTRIC
LAYER FORMED THEREON**)
)
Examiner : Unknown

ESTABLISHMENT OF RIGHT OF ASSIGNEE TO TAKE ACTION
AND
REVOCATION AND POWER OF ATTORNEY

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Dear Sir:

The undersigned is empowered to act on behalf of the assignee below (the "Assignee"). A true copy of the original Assignment of the above-captioned application from the inventor(s) to the Assignee is attached hereto. This Assignment represents the entire chain of title of this invention from the Inventor(s) to the Assignee.

I declare that all statements made herein are true, and that all statements made upon information and belief are believed to be true, and further, that these statements were made with the knowledge that willful, false statements and the like so made are punishable by fine or imprisonment, or both, under 18 U.S.C. § 1001, and that willful, false statements may jeopardize the validity of the application, or any patent issuing thereon.

The undersigned hereby revokes any previous powers of attorney in the subject application, and hereby appoints the registrants of Knobbe, Martens, Olson & Bear, LLP, 2040 Main Street, Fourteenth Floor, Irvine, California 92614, Telephone

App. No. : Unknown
Filed : Herewith

(949) 760-0404, **Customer No. 20,995**, as its attorneys with full power of substitution and revocation to prosecute this application and to transact all business in the U.S. Patent and Trademark Office connected herewith. This appointment is to be to the exclusion of the inventor(s) and his attorney(s) in accordance with the provisions of 37 C.F.R. § 3.71.

Please use **Customer No. 20,995** for all communications.

Nitto Denko Corporation

Dated: November 1, 2005

By: 
Masamichi TAKEMOTO

Title: President

Address: 1-1-2, Shimohozumi, Ibaraki-shi, Osaka
567-8680 Japan